

C0805X391J2TACTU

Aliases (C0805X391J2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 390 pF, 5%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 0805, 0.6 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	11 mg	
Shelf Life	78 Weeks	
MSL	1	

390 pF

1 MHz 1.0Vrms

Dimensions	
Chip Size	0805
L	2mm +/-0.3mm
W	1.25mm +/-0.3mm
Т	0.78mm +/-0.20mm
S	0.6mm MIN
В	0.5mm +/-0.25mm

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Т	0.78mm +/-0.20mm
S	0.6mm MIN
В	0.5mm +/-0.25mm
Backaging Specifications	

W	1.25mm +/-0.3mm	Tolerance	5%
Т	0.78mm +/-0.20mm	Voltage DC	200 VDC
S	0.6mm MIN	Dielectric Withstanding Voltage	500 VDC
В	0.5mm +/-0.25mm	Temperature Range	-55/+150°C
		Temp. Coefficient	X8G
Packaging Specifications		Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Packaging	T&R, 180mm, Plastic Tape		
Packaging Quantity 4000	Dissipation Factor	0.1% 1 MHz 1.0Vrms	
		Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
		Insulation Resistance	100 GOhms

Specifications

Measurement Condition

Capacitance

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